



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Chan, et al.
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Title: **MULTI-DIE MODULE AND METHOD THEREOF**

Assistant Commissioner for Patents
U.S. Patent and Trademark Office
Washington, D.C. 20231

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2-13-02 **KARENINA OLIVER**
Date Karenina Oliver

PRELIMINARY AMENDMENT

Dear Sir:

Please enter the following amendment into the above-identified application before examination on the merits thereof. Marked-up versions of the amendments presented below are provided in the corresponding exhibits at the end of this amendment.

IN THE DRAWINGS

Subject to the approval of the Examiner, it is respectfully requested that the enclosed substitute drawings, corresponding to FIG. 1, 4-6 and 9 replace the original drawings filed with the above-identified application. A copy of the drawings corresponding to FIG. 1, 4-6 and 9, with changes indicated in red, is also enclosed in Exhibit A.

IN THE SPECIFICATION

Please replace paragraph beginning on page 4, line 17 with the following:

FIG. 4 illustrates the partially completed multi-die module of FIG. 3, after unpackaged semiconductor die 110 has been encapsulated with encapsulation material 180. Some examples of encapsulation material 180 are epoxy, metal cap or silicon coatings. Encapsulation material 180 may be dry molded or liquid molded depending on the type of encapsulation material desired. At this stage, solder balls 160 may be added to the bottom of multi-die module substrate 140 to provide for future connection of the completed package module 100 (FIG. 1) to a circuit board and/or other system. In order to facilitate interchangeability with many standard packages,